

ABSTRACT OF THE DISCLOSURE

According to one aspect of the invention, a semiconductor substrate, or wafer, processing apparatus is provided. The wafer processing apparatus may include a frame, a semiconductor substrate support, a dispense head connected to the frame to dispense a semiconductor processing fluid onto a substrate on the support, and a catch cup, having a top section and a mid-section, connected to the frame around the wafer support. A portion of an inner surface of the top section may not face towards, or face away from, a central axis of the semiconductor substrate. An upper surface of the mid-section may have substantially no horizontal portions.